

Atty. Docket No. CPAC 1003-1
Appl. No. 09/802,664

PATENT

21. The method of claim 1, further comprising, prior to pressing the first and second members against one another, dispensing a curable adhesive onto a mating surface of the IC chip.


REMARKS

Claims 18 - 21 are newly added by amendment herein. No new matter is introduced by the amendment, and entry thereof is requested. Claims 1 - 21 are in the application. In a paper filed June 28, 2002, Applicant elected claims 1 - 9 ("Group I"), for prosecution in this application. These claims and new claims 18 - 21 are all drawn to a method for forming a "flip chip interconnection structure" and to a flip chip interconnection structure made by the method and, accordingly, all of claims 1 - 9 and 18 - 21 should be considered in this application. Examination of the application, as amended, is requested.

Applicant thanks Examiner Lee for communicating by telephone with Applicant's representative, undersigned, regarding the status of the application. This Second Preliminary Amendment is being filed prior to the mailing of a first Office action on the merits. If the Examiner determines that an additional fee may be required in connection with this paper, the Commissioner is authorized to charge such fee to Deposit Account 50-0869 (Order No. CPAC 1003-1).

If the Examiner determines that a conference would facilitate prosecution of this application, the Examiner is invited to telephone Applicants' representative, undersigned, at the telephone number set out below.

Respectfully submitted,


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